

*Amendments to the Claims*

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-11. *(Canceled)*

12. *(Previously Presented)* A system configured to reduce wafer slipping, comprising:

a wafer chuck configured to receive a wafer; and  
an expandable annular tube coupled to the wafer chuck and configured to expand the wafer chuck without substantially expanding the wafer, such that an initial stress at an interface between the wafer and the wafer chuck is created, wherein the expandable annular tube is sealed to be pressurized and configured to expand to in turn expand the wafer chuck when pressurized.

13. *(Canceled)*

14. *(Previously Presented)* The system of claim 12, wherein said annular tube is coupled to an outer edge of said wafer chuck.

15. *(Withdrawn)* The system of claim 13, wherein said annular ring fits within a cavity in said wafer chuck.

16. - 22.        *(Canceled)*

23.    *(Previously Presented)* The system of claim 12, wherein said annular tube is configured to expand said wafer chuck in a uniform manner.

24.    *(Previously Presented)* The system of claim 12, wherein said annular tube comprises a metal.

25.    *(Previously Presented)* The system of claim 12, wherein said annular tube comprises a plastic.

26.    *(Previously Presented)* The system of claim 12, wherein said annular tube includes a cavity, and wherein the cavity is configured to be filled with one of a gas and a liquid.

27.    *(Previously Presented)* The system of claim 12, further comprising:  
a temperature sensor coupled to the wafer chuck.

28.    *(Previously Presented)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by vacuum clamping.

29.    *(Previously Presented)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by electrostatic clamping.